

2MBI100VA-060-50

IGBT Modules

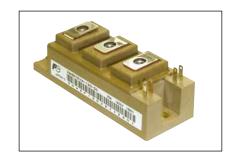
IGBT MODULE (V series) 600V / 100A / 2 in one package

Features

High speed switching Voltage drive Low Inductance module structure

Applications

Inverter for Motor Drive AC and DC Servo Drive Amplifier Uninterruptible Power Supply Industrial machines, such as Welding machines



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings (at T_c=25°C unless otherwise specified)

Items	Sy		Conditions		Maximum ratings	Units	
Collector-Emitter voltage		Vces			600	V	
Gate-Emitter voltage		V _{GES}			±20	V	
Collector current		Ic	Continuous	Tc=100°C	100		
		I _{C pulse}	1ms	1ms		Α	
		-Ic					
		-I _{C pulse}	1ms				
Collector power dissipation		Pc	1 device		650		
Junction temperature		Tj			175		
Operating junction temperature (under switching conditions)		T _{jop}			150	°C	
Case temperature		Tc			125	·	
Storage temperature		T _{stg}				ı	
Isolation voltage	between terminal and copper base (*1)	Viso	AC : 1min.		2500	VAC	
Screw torque	Mounting (*2)	-			5.0	N m	
	Terminals (*3)	-			5.0	IN III	

Note *1: All terminals should be connected together when isolation test will be done.

Note *2: Recommendable Value : 3.0-5.0 Nm (M5 or M6) Note *3: Recommendable Value : 2.5-3.5 Nm (M5)

● Electrical characteristics (at T_j= 25°C unless otherwise specified)

Items	Symbols	Conditions		Characteristics			Units
items	Symbols			min.	typ.	max.	Units
Zero gate voltage collector current	Ices	V _{GE} = 0V, V _{CE} = 600V		-	-	1.0	mA
Gate-Emitter leakage current	Iges	V _{CE} = 0V, V _{GE} = ±20V		-	-	200	nA
ate-Emitter threshold voltage $V_{GE (th)}$ $V_{CE} = 20V, I_C = 100 mA$		V _{CE} = 20V, I _C = 100mA		6.2	6.7	7.2	V
	M	V _{GE} = 15V I _C = 100A	T _j =25°C	-	1.70	2.15	V
	VCE (sat)		T _j =125°C	-	2.00	-	
Collector Emitter acturation voltage	(terminal)		T _j =150°C		2.20		
Collector-Emitter saturation voltage	VCE (sat)	V _{GE} = 15V I _C = 100A	T _j =25°C	-	1.60	2.05	
			T _j =125°C	-	1.90	-	
	(chip)		T _j =150°C		2.10		
Internal gate resistance	R _{G (int)}	-		-	9	-	Ω
Input capacitance	Cies	$V_{CE} = 10V, V_{GE} = 0V, f = 1MHz$		-	6.4	-	nF
	ton	V _{cc} = 300V L _s = 30nH I _c = 100A V _{se} = ±15V		-	650	-	nsec
Turn-on time	tr			-	300	-	
	t _{r (i)}			-	100	-	
Turn-off time	toff	$R_G = 13\Omega$		-	600	-	
Turn-on time	tr	$T_{j} = 150^{\circ}C$		-	40	-	
	VF	V _{GE} = 0V I _F = 100A	T _j =25°C	-	1.65	2.10	V
Forward on voltage	(terminal)		T _j =125°C	-	1.55	-	
	(terrillial)		T _j =150°C		1.52		
	VF	V _{GE} = 0V I _F = 100A	T _j =25°C	-	1.60	2.05	
	1		T _j =125°C	-	1.50	-	
	(chip)		T _j =150°C		1.47		
Reverse recovery time	trr	I _E = 100A		-	200	_	nsec

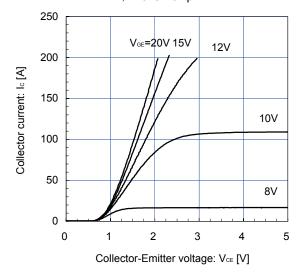
Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Units
items		Conditions	min.	typ.	max.	Ullits
Thermal registeres (delevies)	Ь	IGBT	-	-	0.45	°C/W
Thermal resistance (1device)	R _{th(j-c)}	FWD	-	-	0.80	
Contact thermal resistance (1device) (*4)	R _{th(c-f)}	with Thermal Compound	-	0.050	-	

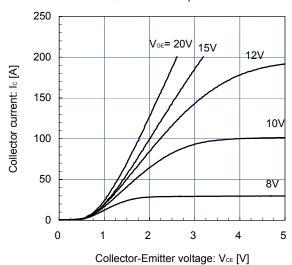
Note *4: This is the value which is defined mounting on the additional cooling fin with thermal compound.

■ Characteristics (Representative)

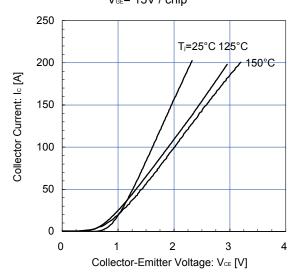
Collector current vs. Collector-Emitter voltage (typ.) T_i = 25°C / chip



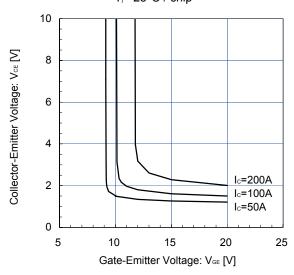
Collector current vs. Collector-Emitter voltage (typ.) T_i= 150°C / chip



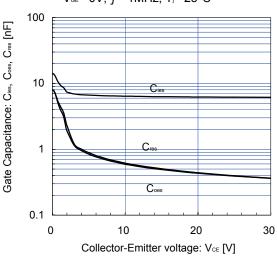
Collector current vs. Collector-Emitter voltage (typ.) V_{GE} = 15V / chip



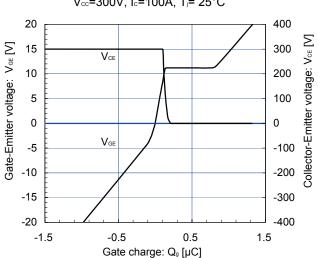
Collector-Emitter voltage vs. Gate-Emitter voltage T_j= 25°C / chip

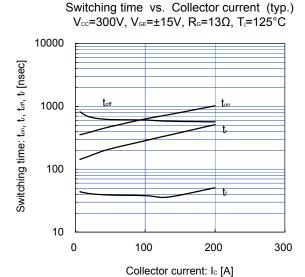


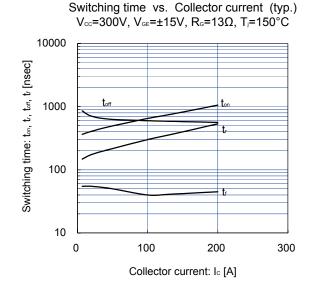
Gate Capacitance vs. Collector-Emitter Voltage V_{GE} = 0V, f= 1MHz, T_{J} = 25°C

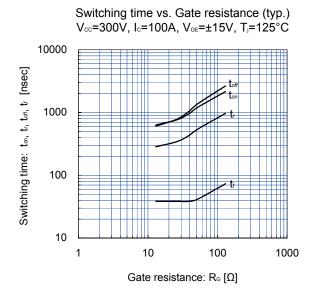


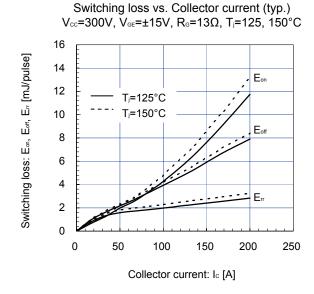
Dynamic Gate Charge (typ.) V_{cc}=300V, I_c=100A, T_i= 25°C

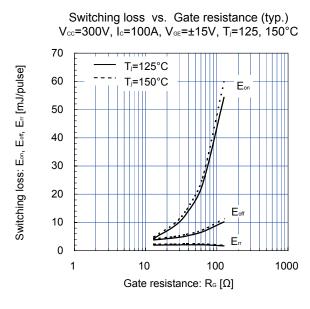


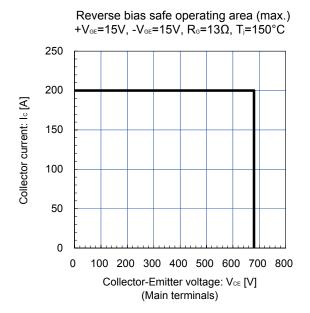




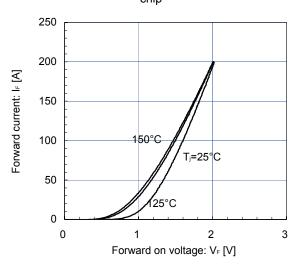




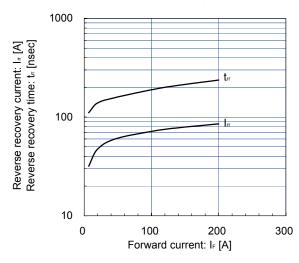




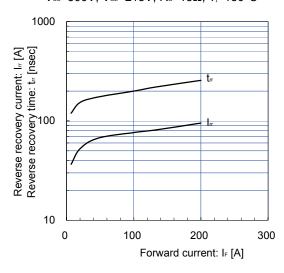
Forward Current vs. Forward Voltage (typ.) chip



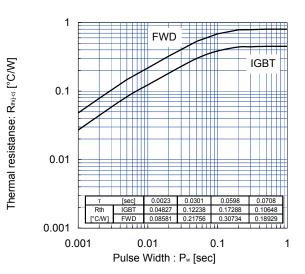
Reverse Recovery Characteristics (typ.) V_{CC} =300V, V_{GE} =±15V, R_{G} =13 Ω , T_{j} =125°C



Reverse Recovery Characteristics (typ.) V_{CC} =300V, V_{GE} =±15V, R_{G} =13 Ω , T_{j} =150°C

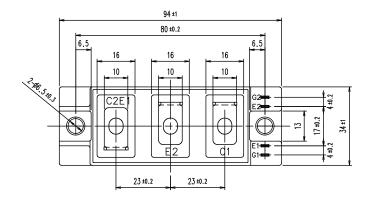


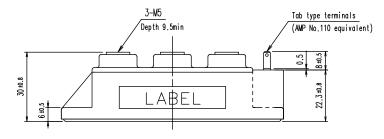
Transient Thermal Resistance (max.)



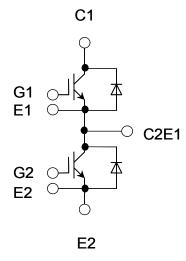
http://www.fujielectric.com/products/semiconductor/

■ Outline Drawings, mm





■ Equivalent Circuit Schematic



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